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|  | ITk Pixel – Outer Endcaps Loaded Local SupportsATLAS ITk-Pixel Project  |
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| Local Supports Loadingfor the ITk Pixel Outer EndcapsProvided for the ITk Pixel Outer System Loaded Local Supports Preliminary Readiness Review28 February – xxx 2024This document describes the procedures and equipment for the loading of modules and on-detector services in the ITk Pixel Outer Endcaps. It also describes the validation of these procedures and equipment. |
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Gabriele Chiodini

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Juliette Martin

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Daniel Hynds